

THC63LVDF84B/THC63LVDF64B

LVDS 24Bit/18Bit COLOR HOST-LCD PANEL INTERFACE RECEIVER

General Description

The THC63LVDF84B/THC63LVDF64B receiver supports wide VCC range(2.5~3.6V). At single 2.5V supply, the THC63LVDF84B/THC63LVDF64B reduces EMI and power consumption.

The THC63LVDF84B receiver convert the four LVDS(Low Voltage Differential Signaling) data streams back into 28bits of CMOS/TTL data with falling edge clock.

At a transmit clock frequency of 85MHz, 28bits of RGB data and 4bits of LCD timing and control data (HSYNC, VSYNC, CNTL1, CNTL2) are transmitted at a rate of 2.3Gbps.

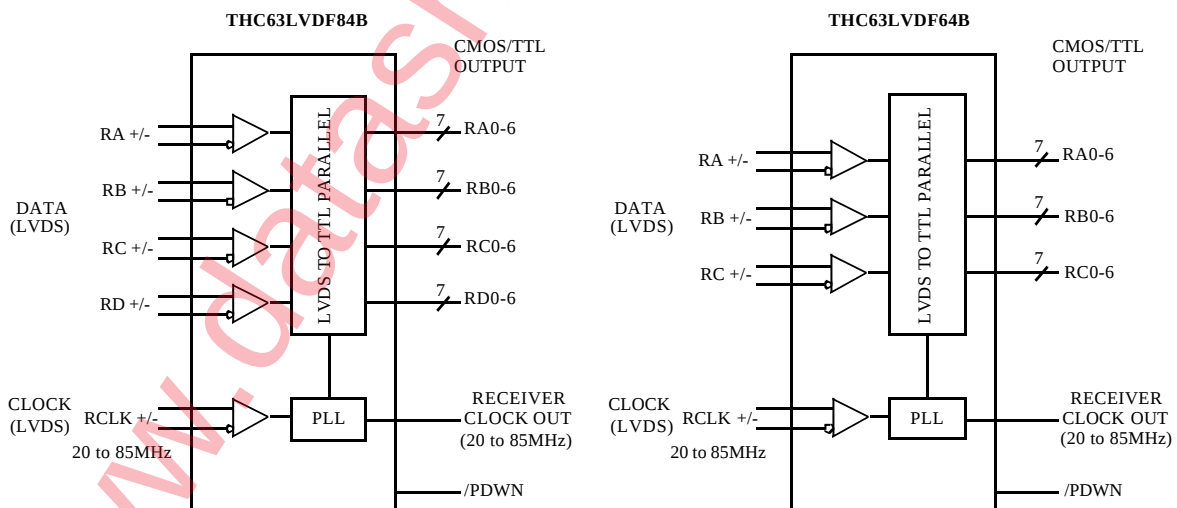
Also the THC63LVDF64B receiver convert the three LVDS data streams back into 21bits of CMOS/TTL data with falling edge clock.

At a transmit clock frequency of 85MHz, 21bits of RGB data and 4bits of LCD timing and control data (HSYNC, VSYNC, CNTL1, CNTL2) are transmitted at a rate of 1.78Gbps.

Features

- Wide VCC range: 2.5~3.6V
- Wide dot clock range: 20-85MHz suited for VGA, SVGA, XGA and SXGA (VCC=3.0~3.6V)
- Wide dot clock range: 20-70MHz suited for VGA, SVGA, XGA and SXGA (VCC=2.5V~3.6V)
- PLL requires No external components
- Rx power consumption < 80mW @VCC 2.5V, 65MHz Grayscale
- Power-Down Mode
- Low profile 56 Lead or 48 Lead TSSOP Package
- Pin compatible with THC63LVDF84A/F64A

Block Diagram



(140-595Mbit/On Each LVDS Channel)

Pin Out

THC63LVDF84B

RC3	1	56	VCC
RD6	2	55	RC2
RC4	3	54	RC1
GND	4	53	RC0
RC5	5	52	GND
RC6	6	51	RB6
RD0	7	50	RD5
LVDSGND	8	49	RD4
RA-	9	48	VCC
RA+	10	47	RB5
RB-	11	46	RB4
RB+	12	45	RB3
LVDSVCC	13	44	GND
LVDSGND	14	43	RB2
RC-	15	42	RD3
RC+	16	41	RD2
RCLK-	17	40	VCC
RCLK+	18	39	RB1
RD-	19	38	RB0
RD+	20	37	RA6
LVDSGND	21	36	GND
PLL GND	22	35	RA5
PLL VCC	23	34	RD1
PLL GND	24	33	RA4
/PDWN	25	32	RA3
CLKOUT	26	31	VCC
RA0	27	30	RA2
GND	28	29	RA1

THC63LVDF64B

RC3	1	48	VCC
RC4	2	47	RC2
GND	3	46	RC1
RC5	4	45	RC0
RC6	5	44	GND
N/C	6	43	RB6
LVDSGND	7	42	VCC
RA-	8	41	RB5
RA+	9	40	RB4
RB-	10	39	RB3
RB+	11	38	GND
LVDSVCC	12	37	RB2
LVDSGND	13	36	VCC
RC-	14	35	RB1
RC+	15	34	RB0
RCLK-	16	33	RA6
RCLK+	17	32	GND
LVDSGND	18	31	RA5
PLL GND	19	30	RA4
PLL VCC	20	29	RA3
PLL GND	21	28	VCC
/PDWN	22	27	RA2
CLKOUT	23	26	RA1
RA0	24	25	GND

THC63LVDF84B Pin Description

Pin Name	Pin #	Type	Description
RA+, RA-	9, 10	LVDS IN	LVDS Data Inputs
RB+, RB-	11, 12	LVDS IN	
RC+, RC-	15, 16	LVDS IN	
RD+, RD-	19, 20	LVDS IN	
RCLK+, RCLK-	17, 18	LVDS IN	LVDS Clock Inputs
RA0~RA6	27,29,30,32,33,35,37	OUT	Pixel Data Outputs
RB0~RB6	38,39,43,45,46,47,51	OUT	
RC0~RC6	53,54,55,1,3,5,6	OUT	
RD0~RD6	7,34,41,42,49,50,2	OUT	
CLKOUT	26	OUT	Pixel Clock Output
/PDWN	25	IN	H: Normal operation L: Power down (all output are Hi-Z)
VCC	31,40,48,56	Power	Power Supply Pins for TTL outputs and digital circuitry
GND	28,36,44,52	Ground	Ground Pins for TTL outputs and digital circuitry
LVDSVCC	13	Power	Power Supply Pin for LVDS inputs
LVDSGND	8,14,21	Ground	Ground Pins for LVDS inputs
PLLVCC	23	Power	Power Supply Pin for PLL circuitry
PLLGND	22,24	Ground	Ground Pins for PLL circuitry

THC63LVDF64B Pin Description

Pin name	Pin #	Type	Description
RA+, RA-	8,9	LVDS IN	LVDS Data Inputs
RB+, RB-	10,11	LVDS IN	
RC+, RC-	14,15	LVDS IN	
RCLK+, RCLK-	16,17	LVDS IN	LVDS Clock Inputs
RA0~RA6	24,26,27,29,30,31,33	OUT	Pixel Data Outputs
RB0~RB6	34,35,37,39,40,41,43	OUT	
RC0~RC6	45,46,47,1,2,4,5	OUT	
CLKOUT	23	OUT	Pixel Clock Output
/PDWN	22	IN	H: Normal operation L: Power down (all output are Hi-Z)
VCC	28,36,42,48	Power	Power Supply Pins for TTL outputs and digital circuitry
GND	3,25,32,38,44	Ground	Ground Pins for TTL outputs and digital circuitry
LVDSVCC	12	Power	Power Supply Pin for LVDS inputs
LVDSGND	7,13,18	Ground	Ground Pins for LVDS inputs
PLLVCC	20	Power	Power Supply Pin for PLL circuitry
PLLGND	19,21	Ground	Ground Pins for PLL circuitry

Electrical Characteristics**CMOS/TTL DC SPECIFICATIONS**

VCC = 2.5V ~ 3.6V, Ta = -10 °C ~ +70 °C

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Units
V _{IH}	High Level Input Voltage		2.0		VCC	V
V _{IL}	Low Level Input Voltage		GND		0.8	V
V _{OH1}	High Level Output Voltage	VCC = 3.0V ~ 3.6V I _{OH} = -4mA	2.4			V
V _{OL1}	Low Level Output Voltage	VCC = 3.0V ~ 3.6V I _{OL} = 4mA			0.4	V
V _{OH2}	High Level Output Voltage	VCC = 2.5V ~ 3.6V I _{OH} = -2mA	2.1			V
V _{OL2}	Low Level Output Voltage	VCC = 2.5V ~ 3.6V I _{OL} = 2mA			0.4	V
I _{IN}	Input Current	0V ≤ V _{IN} ≤ VCC			±10	uA

LVDS RECEIVER DC SPECIFICATIONS

VCC = 2.5V ~ 3.6V, Ta = -10 °C ~ +70 °C

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Units
V _{TH}	Differential Input High Threshold	VOC = +1.2V			100	mV
V _{TL}	Differential Input Low Threshold		-100			mV
I _{IN}	Input Current	V _{IN} = +2.4V/0V VCC = 3.6V			±10	uA

Absolute Maximum Ratings¹

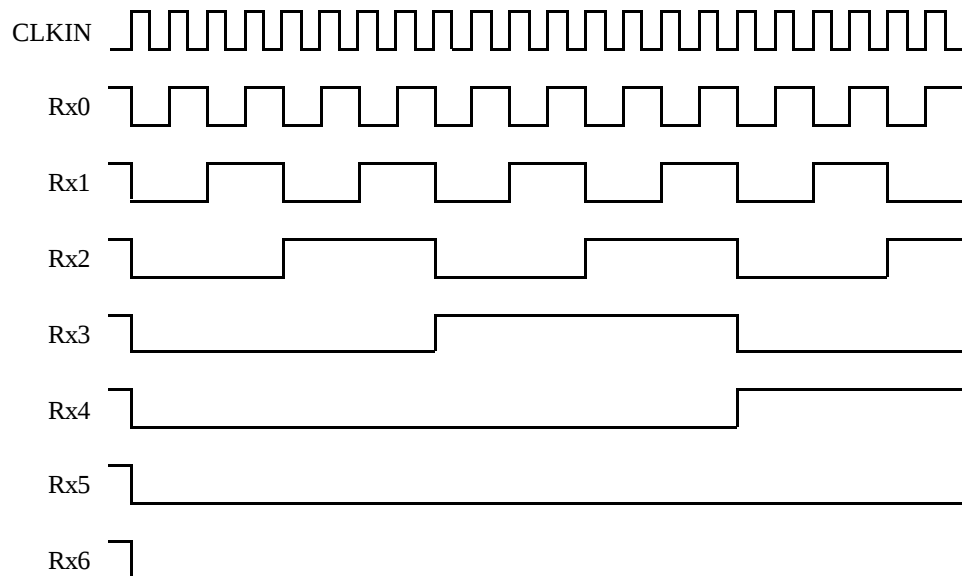
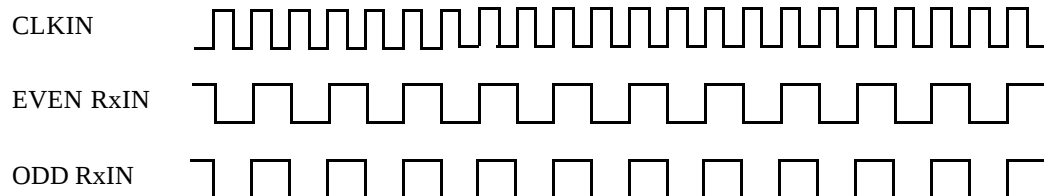
Supply Voltage (Vcc)	-0.3 to +4V
CMOS/TTL Input Voltage	-0.3 to (Vcc + 0.3V)
CMOS/TTL Output Voltage	-0.3V to (Vcc + 0.3V)
LVDS Receiver Input Voltage	-0.3V to (Vcc + 0.3V)
Junction Temperature	+150°C
Storage Temperature Range	-65°C to +150°C
Lead Temperature (Soldering, 4sec.)	+260°C
Maximum Power Dissipation@25°C	1.4W

1. "Absolute Maximum Ratings" are those valued beyond which the safety of the device can not be guaranteed. They are not meant to imply that the device should be operated at these limits. The tables of "Electrical Characteristics" specify conditions for device operation.

Supply Current

VCC = 2.5V ~ 3.6V, Ta = -10 °C ~ +70 °C

Symbol	Parameter	Condition(*)		Typ.	Max.	Units
I _{RCCG}	Receiver Supply Current 16Grayscale Pattern	CL=8pF, VCC=3.3V	f = 65MHz	41	53	mA
			f = 85MHz	52	64	mA
		CL=8pF, VCC=2.5V	f = 65MHz	30	42	mA
I _{RCCW}	Receiver Supply Current Worst Case Pattern	CL=8pF, VCC=3.3V	f = 65MHz	72	94	mA
			f = 85MHz	84	96	mA
		CL=8pF, VCC=2.5V	f = 65MHz	42	64	mA
I _{RCCS}	Receiver Power Down Supply Current	/PDWN = L			10	μA

16 Gray Scale PatternWorst Case Pattern

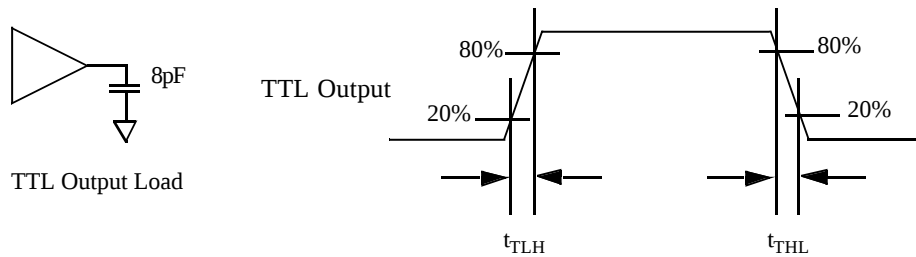
Switching Characteristics

VCC = 2.5V ~ 3.6V, Ta = -10°C ~ +70°C

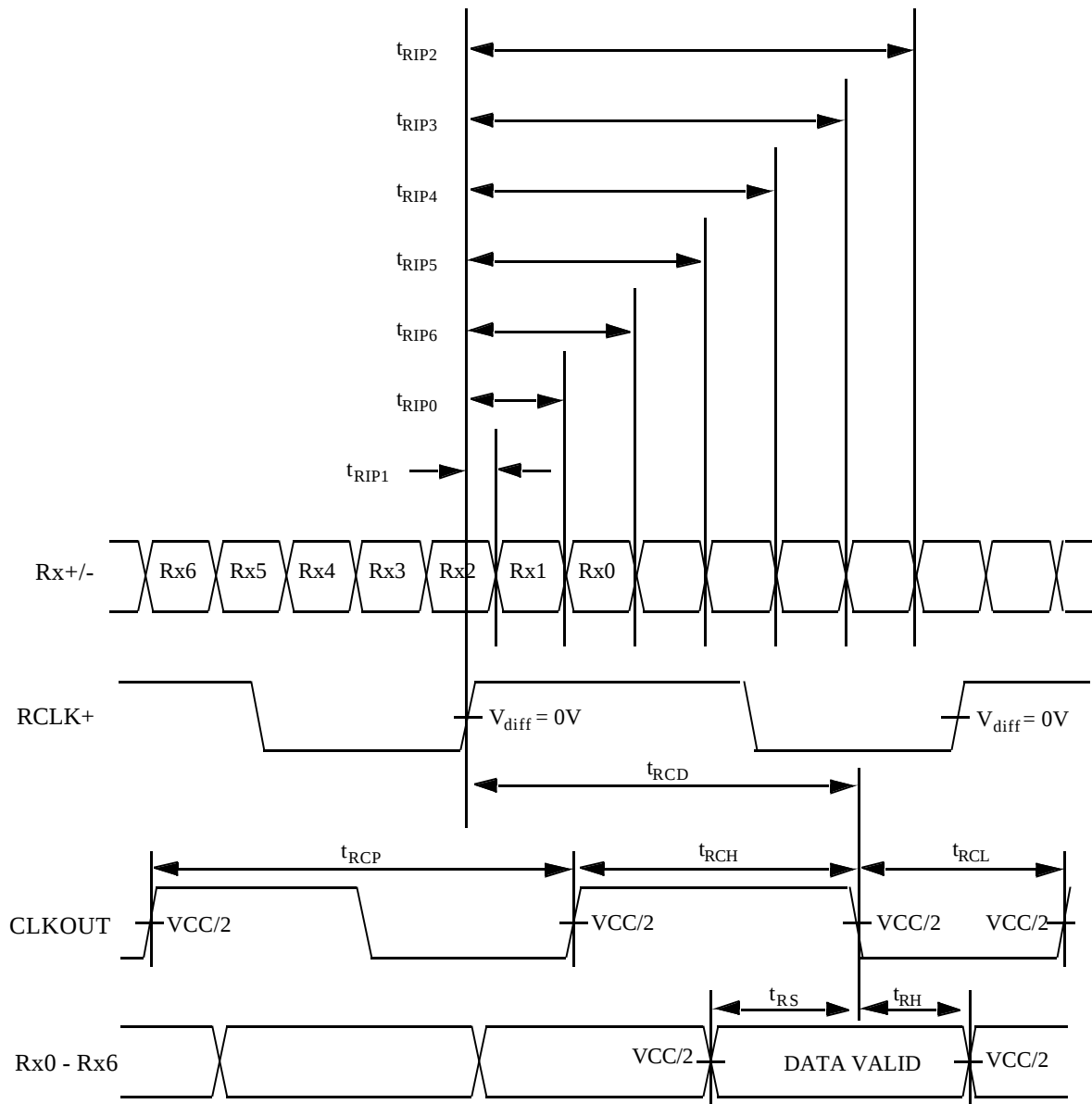
Symbo l	Parameter		Min.	Typ.	Max.	Unit s
t_{RCP}	CLK OUT Period	VCC = 3.0 - 3.6V	11.76	T	50.0	ns
		VCC = 2.5 - 3.6V	14.28	T	50.0	ns
t_{RCH}	CLK OUT High Time			4T/7		ns
t_{RCL}	CLK OUT Low Time			3T/7		ns
t_{RCD}	RCLK +/- to CLK OUT Delay			5T/7		ns
t_{RS}	TTL Data Setup to CLK OUT		3T/7-2.5			ns
t_{RH}	TTL Data Hold from CKL OUT		4T/7-3.5			ns
t_{TLH}	TTL Low to High Transition Time			3.0	5.0	ns
t_{THL}	TTL High to Low Transition Time			3.0	5.0	ns
t_{RIP1}	Input Data Position0 (T = 11.76ns)		-0.4	0.0	0.4	ns
t_{RIP0}	Input Data Position1 (T = 11.76ns)		T/7-0.4	T/7	T/7+0.4	ns
t_{RIP6}	Input Data Position2 (T = 11.76ns)		2T/7-0.4	2T/7	2T/7+0.4	ns
t_{RIP5}	Input Data Position3 (T = 11.76ns)		3T/7-0.4	3T/7	3T/7+0.4	ns
t_{RIP4}	Input Data Position4 (T = 11.76ns)		4T/7-0.4	4T/7	4T/7+0.4	ns
t_{RIP3}	Input Data Position5 (T = 11.76ns)		5T/7-0.4	5T/7	5T/7+0.4	ns
t_{RIP2}	Input Data Position6 (T = 11.76ns)		6T/7-0.4	6T/7	6T/7+0.4	ns
t_{RPLL}	Phase Lock Loop Set				10.0	ms

AC Timing Diagrams

TTL Output



AC Timing Diagrams

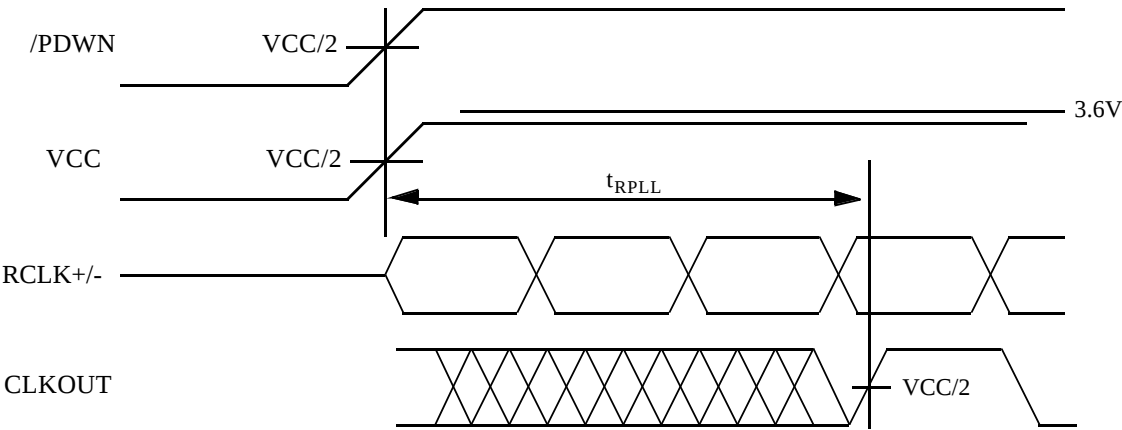


Note:

1) $V_{diff} = (RA+) - (RA-), \dots, (RCLK+) - (RCLK-)$

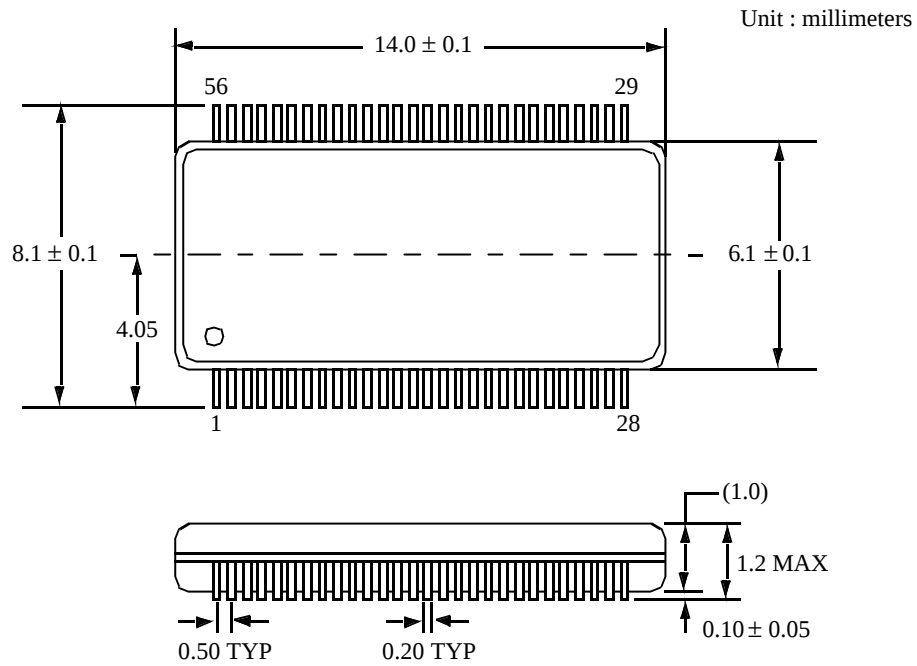
AC Timing Diagrams

Phase Lock Loop Set Time

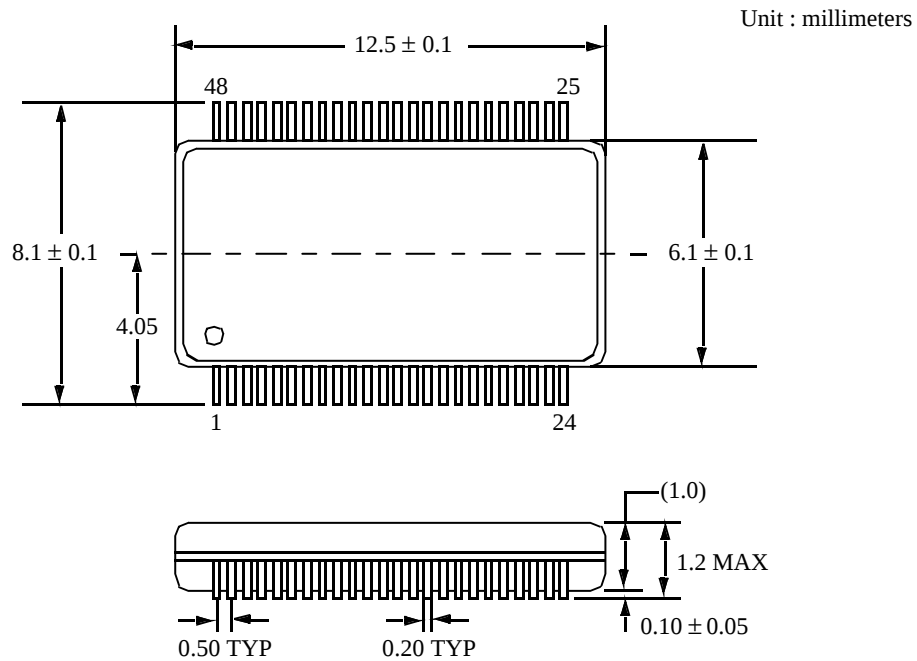


Package

56 Lead Molded Thin Shrink Small Outline Package, JEDEC



48 Lead Molded Thin Shrink Small Outline Package, JEDEC



Notes to Users:

1. The contents of this data sheet are subject to change without prior notice.
2. Circuit diagrams shown in this data sheet are examples of application. Therefore, please pay sufficient attention when designing circuits. Even if there are incorrect descriptions, we are not responsible for any problem due to them. Please note that incorrect descriptions sometimes cannot be corrected immediately if found.
3. Our copyright and know-how are included in this data sheet. Duplication of the data sheet and disclosure to other persons are strictly prohibited without our permission.
4. We are not responsible for any problems of industrial proprietorship occurring during THC63LVDF84B/THC63LVDF64B use, except for those directly related to THC63LVDF84B/THC63LVDF64B's structure, manufacture or functions. THC63LVDF84B/THC63LVDF64B is designed on the premise that it should be used for ordinary electronic devices. Therefore, it shall not be used for applications that require extremely high-reliability (space equipment, nuclear control equipment, medical equipment that affects people's lives, etc.). In addition, when using THC63LVDF84B/THC63LVDF64B for traffic signals, safety devices and control/safety units in transportation equipment, etc., appropriate measures should be taken.
5. We are making the utmost effort to improve the quality and reliability of our products. However, there is a very slight possibility of failure in semiconductor devices. To avoid damage to social or official organizations, much care should be taken to provide sufficient redundancy and fail-safe design.
6. No radiation-hardened design is incorporated in THC63LVDF84B/THC63LVDF64B.
7. Judgment on whether THC63LVDF84B/THC63LVDF64B comes under strategic products prescribed by the Foreign Exchange and Foreign Trade Control Law is the user's responsibility.
8. This technical document was provisionally created during development of THC63LVDF84B/THC63LVDF64B, so there is a possibility of differences between it and the product's final specifications. When designing circuits using THC63LVDF84B/THC63LVDF64B, be sure to refer to the final technical documents.

THine Electronics, Inc.

Matsuda Yaesudori Bldg. 6F
1-10-7, Hatchobori,
Chuo-ku, Tokyo, 104-0032 Japan
Tel: 81-3-3555-0666
Fax: 81-3-3555-0677